PATENT

Case Docket No. UNIU40.005APC
Date: April 21, 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s)	:	Masahiko NAKAMORI, et al.
App. No.	:	10/536,621
Filed	:	May 26, 2005
For	:	POLISHING PAD AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE
Art Unit	:	1763

U.S. PATENT AND TRADEMARK OFFICE
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Dear Sir:

REQUEST FOR CORRECTED PUBLICATION

Applicants noted a error in the title of the invention in the Publication for the above-identified patent application. The correct title is --POLISHING PAD AND METHOD **OF PRODUCING** SEMICONDUCTOR DEVICE-- not "POLISHING PAD AND METHOD **FOR MANUFACTURING** SEMICONDUCTOR DEVICE". Please make this correction in the Patent and Trademark Office and issue a corrected Publication. As this error appears to have been made at the U.S. Patent and Trademark Office, we believe no fees to be required. However, should any fees be necessary for this request, please charge them to our deposit Account No. 11-1410.

Enclosed in support of this Request are the following:

(X) A Copy of a Notice of Publication of Application and a face sheet of the Publication.

(X) A Copy of the Declaration and Power of Attorney.

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APPLICATION NUMBER	FILING OR 371 (c) DATE	FIRST NAMED APPLICANT	ATTY. DOCKET NO.
10/536,621	05/26/2005	Masahiko Nakamori	UNIU40.005APC

CONFIRMATION NO. 9275

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Title: Polishing pad and method for manufacturing semiconductor device
↳ Please change to --POLISHING PAD AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE--
Publication No. US-2006-0037699-A1
Publication Date: 02/23/2006

NOTICE OF PUBLICATION OF APPLICATION

The above-identified application will be electronically published as a patent application publication pursuant to 37 CFR 1.211, et seq. The patent application publication number and publication date are set forth above.

The publication may be accessed through the USPTO's publically available Searchable Databases via the Internet at www.uspto.gov. The direct link to access the publication is currently http://www.uspto.gov/patft/.

The publication process established by the Office does not provide for mailing a copy of the publication to applicant. A copy of the publication may be obtained from the Office upon payment of the appropriate fee set forth in 37 CFR 1.19(a)(1). Orders for copies of patent application publications are handled by the USPTO's Office of Public Records. The Office of Public Records can be reached by telephone at (703) 308-9726 or (800) 972-6382, by facsimile at (703) 305-8759, by mail addressed to the United States Patent and Trademark Office, Office of Public Records, Alexandria, VA 22313-1450 or via the Internet.

In addition, information on the status of the application, including the mailing date of Office actions and the dates of receipt of correspondence filed in the Office, may also be accessed via the Internet through the Patent Electronic Business Center at www.uspto.gov using the public side of the Patent Application Information and Retrieval (PAIR) system. The direct link to access this status information is currently http://pair.uspto.gov/. Prior to publication, such status information is confidential and may only be obtained by applicant using the private side of PAIR.

Further assistance in electronically accessing the publication, or about PAIR, is available by calling the Patent Electronic Business Center at 703-305-3028.

Pre-Grant Publication Division, 703-605-4283

US 20060037699A1

(19) **United States**

(12) **Patent Application Publication** (10) **Pub. No.: US 2006/0037699 A1**

Nakamori et al. (43) **Pub. Date: Feb. 23, 2006**

Please change to --POLISHING PAD AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE--

(54) **POLISHING PAD AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE**

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(21) Appl. No.: **10/536,621**

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(30) **Foreign Application Priority Data**

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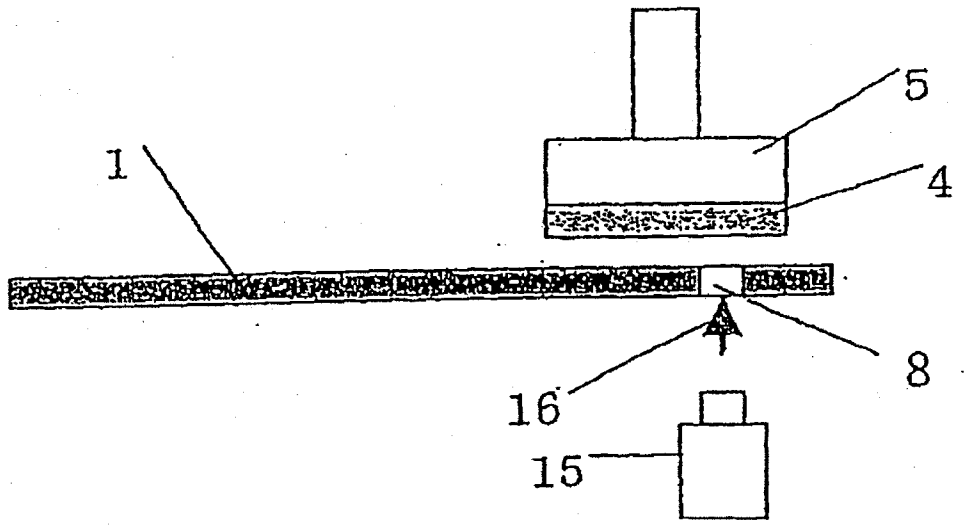
Publication Classification

(51) **Int. Cl.**
C23F 1/00 (2006.01)

(52) **U.S. Cl.** **156/345.12**

(57) **ABSTRACT**

A polishing pad enabling a highly precise optical endpoint sensing during the polishing process and thus having excellent polishing characteristics (such as surface uniformity and in-plane uniformity) is disclosed. A polishing pad enabling to obtain the polishing profile of a large area of a wafer is also disclosed. A polishing pad of a first invention comprises a light-transmitting region having a transmittance of not less than 50% over the wavelength range of 400 to 700 nm. A polishing pad of a second invention comprises a light-transmitting region having a thickness of 0.5 to 4 mm and a transmittance of not less than 80% over the wavelength range of 600 to 700 nm. A polishing pad of a third invention comprises a light-transmitting region arranged between the central portion and the peripheral portion of the polishing pad and having a length (D) in the diametrical direction which is three times or more longer than the length (L) in the circumferential direction.



Attorney's Docket No.

DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled(POLISHING PAD AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE; PCT Application No. PCT/JP2003/015128 filed in the Japanese Receiving Office on November 27, 2003; the documentation for entry into the U.S. national phase of which is attached hereto;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

			Priority Claimed
No.: **2002-343199**	Country: **Japan**	Date Filed: **27/11/02**	**Yes**
No.: **2003-000331**	Country: **Japan**	Date Filed: **06/01/03**	**Yes**
No.: **2003-029477**	Country: **Japan**	Date Filed: **06/02/03**	**Yes**
No.: **2003-064653**	Country: **Japan**	Date Filed: **11/03/03**	**Yes**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

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